1 Form A APSEMI DIP-4 SMD-4 Load Voltage:60V Load Current:3.0A

TSCA Parameter Symbol Units Rating E534710 Load Voltage VL V 60 Load Current А ΙL 3 0.055 On-Resistance Ron Ω I/O Breakdown Voltage 5000 Vrms V/ıo (+) Input 1 \cap $\sqrt{2}$ E1 IF (AC.DC) SMD-4 1 I FD Anode DIP-4 AC/DC 2. LED Cathode

APSEMI PhotoRelays

R

APSEMI Photorelays are the most reliable, technically advanced logic-to-power interface devices. Their basic function is to take a low current signal from a microprocessor to control the switching of both AC and DC loads, while providing an isolation barrier between logic and power. While this function is common to all relays, Photorelays provide distinct advantages over their mechanical counterparts including:

3.4. Drain(MOS FET)

- Long life (No limit on mechanical and electrical
- lifetime)Bounce-free switching
- Higher speed and high frequency switching
- Higher sensitivity (less power consumption)
- Immunity to EMI or RFI

- No have voltaic arc, bounce, and noise More
- resistant to vibration and impact AC or DC load
- switching
 - Small package size

Function

APSEMI PhotoRelays operate by taking a low level input current (<5mA) that energizes an input Infrared LED, which is optically-coupled to a Photo-diode array chip. This IC in turn generates a photo voltage that powers two MOSFETs typically connected in a source-to-source con | guration, allowing for both AC and DC output loads. Photorelay basically move photons to accomplish their switching function, they incur no mechanical wear and tear, providing consistent reliable switching.

Robotics

Aerospace

Process Control

Energy Management

Home/Safety security systems

Reed Relay EMR Replacement

Programmable Controllers

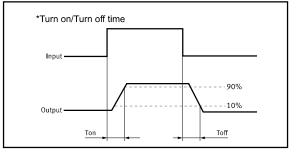
Applications

These advantages make APSEI Photorelays the ideal choice for:

- Telecom/Datacom switching •
- Multiplexers
- Meter reading systems .
- Data acquisition
- Medical equipment .
- Battery monitoring
- I/O Sub-Systems

TPYES

Category	Output rating				Packing quantity	
	Load voltage	Load voltage Load current Package		Part No.		
AC/DC	60V	60V 3.0A DIP4 SMD4	COV 0.04	DIP4	APY252G3E	50pcs/tube
			SMD4	APY252G3EH	1000pcs/1reel	





APY252G3E_EH



Absolute Maximum Ratings (Ta = 25°C)

Item		Symbol	Value	Units	Note	
Continuous LED Current		lF	50	mA		
Input	Peak LED Current	IFP	1000	mA	f=100Hz, duty=1%	
	LED Reverse Voltage	VR	5	V		
	Input Power Dissipation	Pln	75	mW		
Output	Load Voltage	VL	60	V(AC peak or DC)		
	Load Current	l.	3.0	А		
	Peak Load Current	Peak	6.0	А	100ms(1 pulse)	
	Output Power Dissipation	Pout	500	mW		
Total Power Dissipation		Ρτ	650	mW		
I/O Breakdown Voltage		Vı/o	5000	Vrms	RH=60%, 1min	
Operating Temperature		Topr	-40 to +85	°C		
Storage Temperature		Tstg	-40 to +100	°C		
Pin Soldering Temperature		T _{sol}	260	°C	10 sec max.	

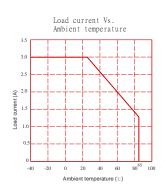
Electrical Specifications (Ambient Temperature: 25°C)

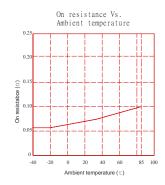
Item		Symbol	MIN.	TYP.	MAX.	Units	Conditions	
LED Forward Voltage		VF	1.2	1.32	1.6	V	I⊧=10mA	
Input	Operation LED Current	F on		1.0	5.0	mA		
	Recovery LED Current	IF off		0.35	0.5	mA		
	Recovery LED Voltage	VF off	0.7			V		
Output	On-Resistance	Ron		0.055	0.085	Ω	I⊧=5mA,I∟=100mA, Time to flow is within 1 sec.	
	Off-State Leakage Current	ILeak	0.01	0.03	0.10	uA	V₋=Rating	
	Output Capacitance	Cout		185		pF	V∟=0, f=1MHz	
Transmis sion	Turn-On Time	Ton	0.2	1.0	2.0	ms	l⊧=5mA, l∟=100mA,	
	Turn-Off Time	Toff	0.04	0.05	0.1	ms		
Coupled	I/O Isolation Resistance	Rı/o	5			GΩ	DC500V	
	I/O Capacitance	Cı/o		0.8	1.5	pF	f=1MHz	

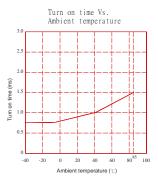
Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value): IF ≥5mA and ≤30mA

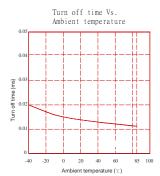
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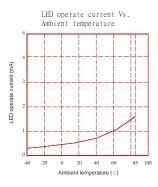
Engineering Data

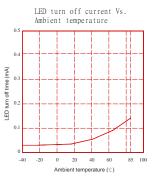




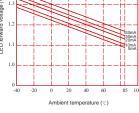


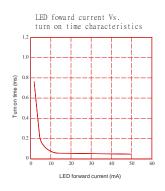




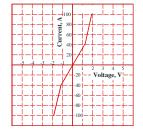


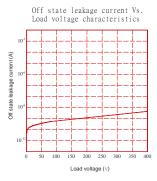
LED forward voltage Vs. Ambient temperature 13 L LED forward voltage (V) 1 i



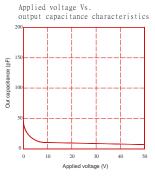


Voltage Vs. currennt characteristics of output at MOS portion





LED foward current Vs. turn off time characteristics 0.1 ns) , e 0.0+ # 0 Turn LED forward current (mA)



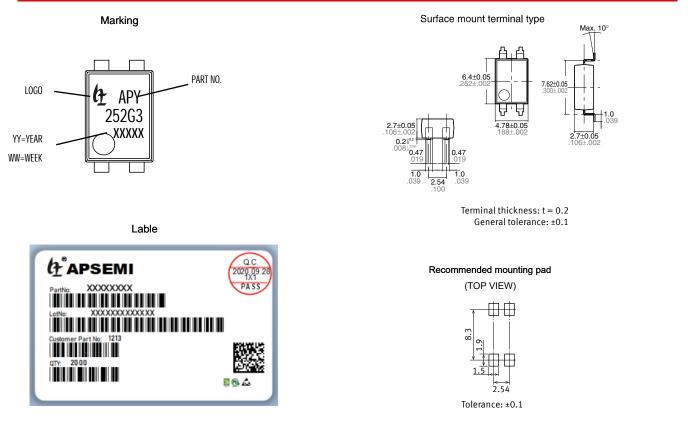
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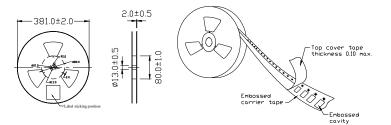
Dimensions and SMD-4 Package Unit: mm

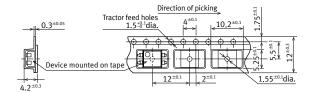
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Tape dimensions (tape reel)



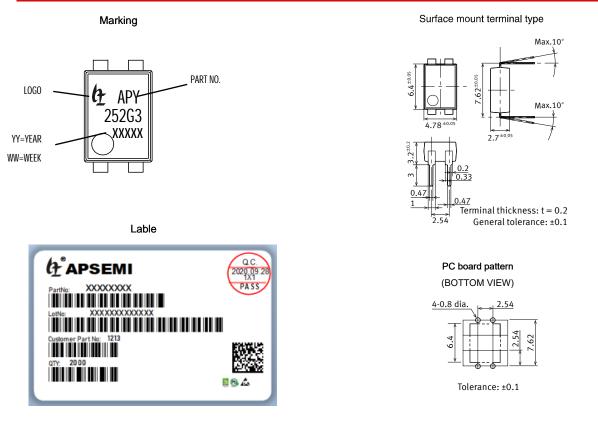


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Dimensions and DIP-4 Package Unit: mm



Tape dimensions (tape reel)

DIP type

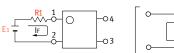
Devices are packaged in a tube so that pin No. 1 is on the stopper B side. Observe correct orientation when mounting them on PC boards.

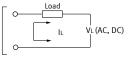




Using Methods

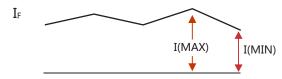
Examples of resistance value to control LED forward current (IF=5mA)





E1	R1 (Approx)
3.3V	300 Ω
5.0V	600 Ω
12V	1.9KΩ
24V	4.1K Ω

LED forward current must be more than 5mA , at I(MIN) ,and less than 30mA , at I(MAX).



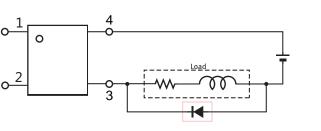
Recommended Operating Conditions

Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value):

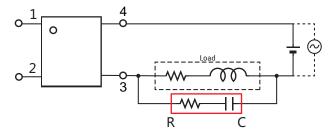
Characteristic	Symbol	Min	Тур.	Max	Unit
Forward current	١ _F	5.0	7.0	30	mA

Protection Circuit

Clamp diode is connected in parallel with the load. Absorb capacity with external diode.



CR Snubber is connected in parallel with the load. Absorb capacity with buffer capacity.



When adding diodes, buffer circuits (C-R), and other protections, they need to be installed near the MOS RELAY to be effective. Adding protection elements may result in a slow reset time, so adjust them according to the actual situation before use.

Note: When developing designs using this product, perform the expected performance of the equipment under the operating conditions recommended by the guidelines in this document. Continuous use under heavy loads (including, but not limited to, the application of high temperatures/current/voltage and significant changes in temperature, etc.) may result in deterioration of the reliability of this product.

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